

[illegible]



N 塑封封装 道 场效应管。

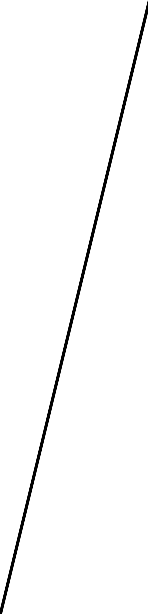
RDS(ON)导通电阻小，SOT23-3 封装，无卤产品。  
Low RDS(ON),SOT23-3 package,HF Product.

电池管庞



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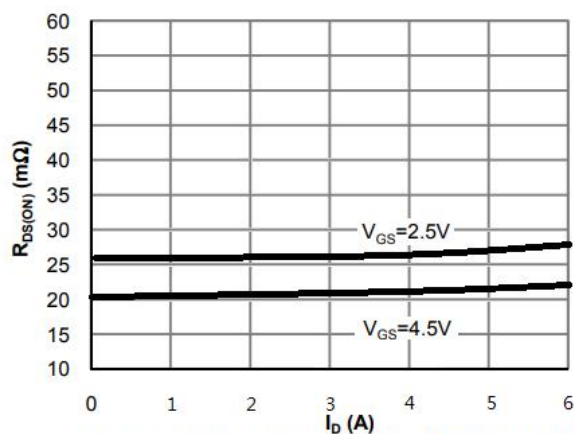
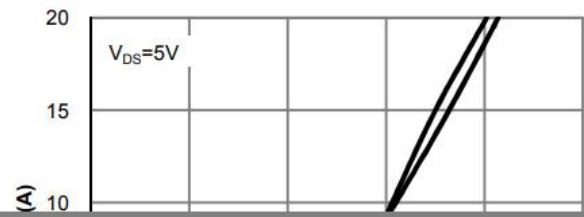
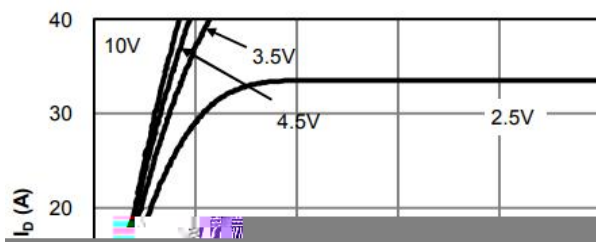


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

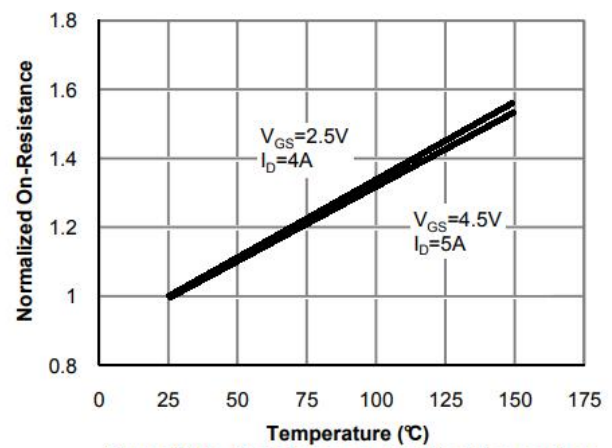


Figure 4: On-Resistance vs. Junction Temperature



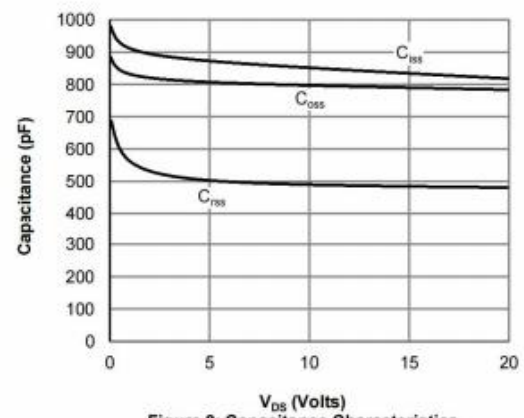
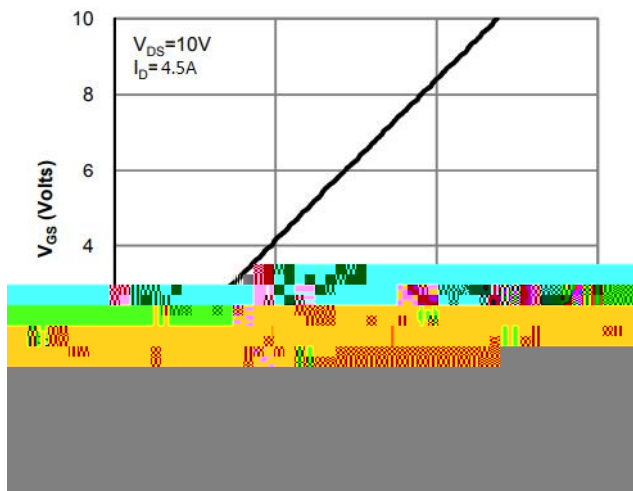
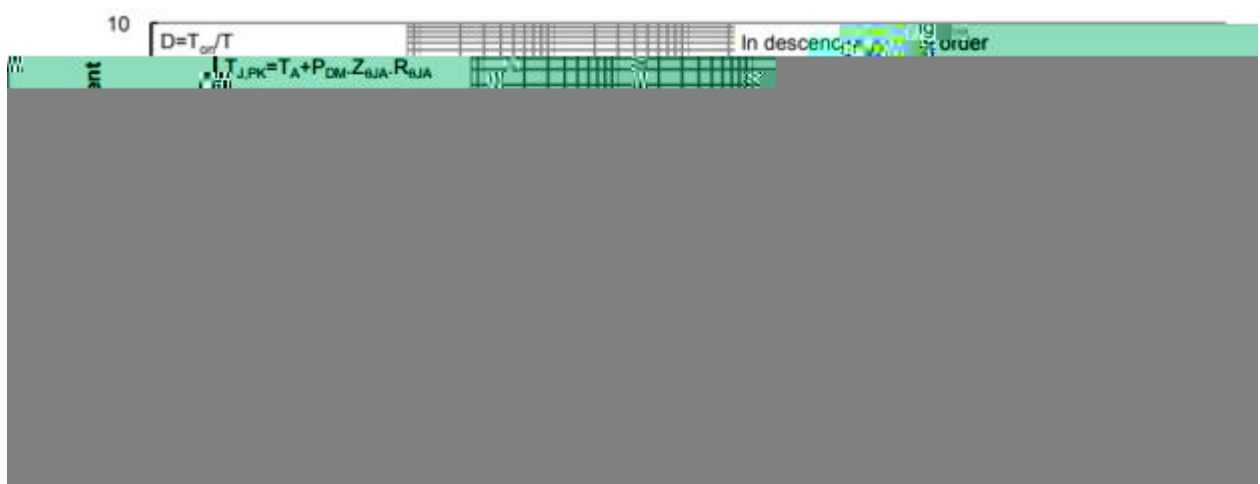
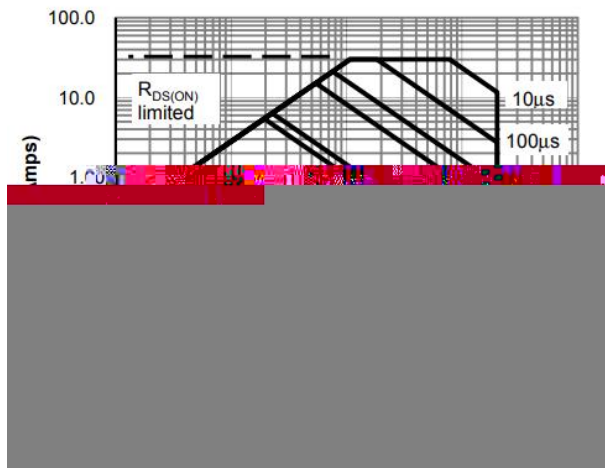
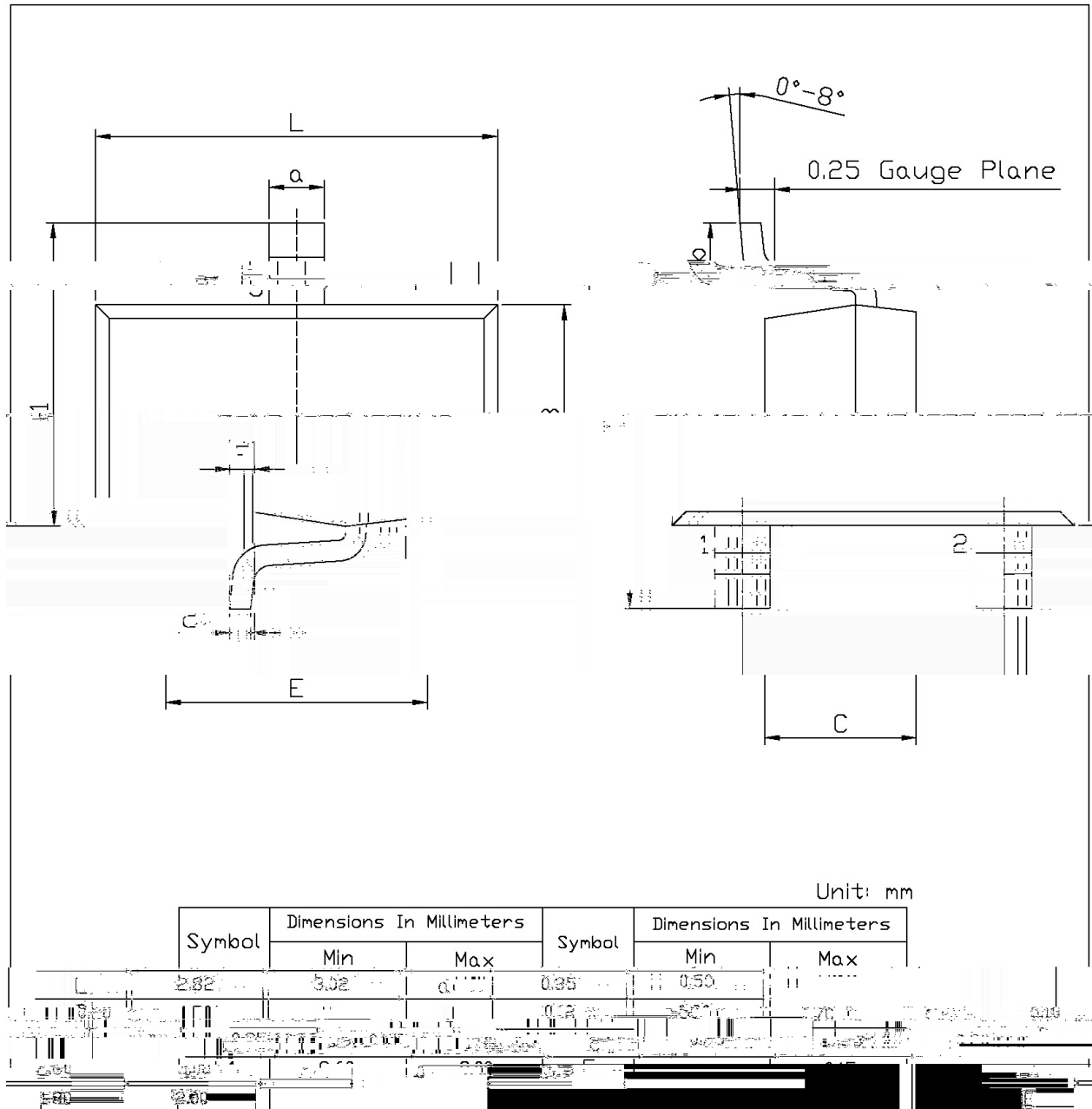
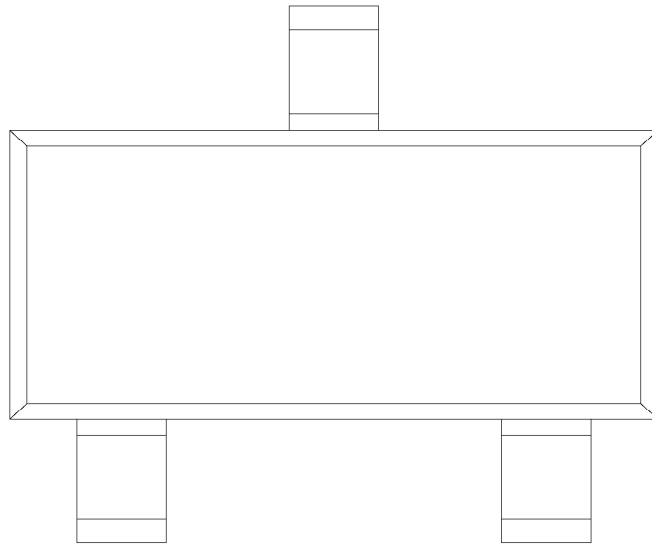


Figure 8: Capacitance Characteristics









Temperature Profile for IR Reflow Soldering(Pb-Free)

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